Unit: mm

TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (L^2 - π -MOSV)

2SJ508

Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain-source ON resistance : $R_{DS}(ON) = 1.35 \Omega \text{ (typ.)}$ • High forward transfer admittance : $|Y_{fs}| = 0.7 \text{ S (typ.)}$

• Low leakage current : $I_{DSS} = -100 \,\mu\text{A} \,(V_{DS} = -100 \,\text{V})$

• Enhancement-mode : $V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -1 \text{ mA)}$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	-100	V
Drain-gate voltage (Ro	_{GS} = 20 kΩ)	V_{DGR}	-100	V
Gate-source voltage		V _{GSS}	±20	V
Drain current	DC (Note 1)	I _D	-1	А
	Pulse (Note 1)	I _{DP}	-3	Α
Drain power dissipation	n	P _D	0.5	W
Drain power dissipation	n (Note 2)	P _D	1.5	W
Single pulse avalanche	e energy (Note 3)	E _{AS}	136.5	mJ
Avalanche current		I _{AR}	-1	Α
Repetitive avalanche e	energy (Note 4)	E _{AR}	0.05	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55~150	°C

1.6MAX. 1.7MAX. 0.4±0.05 0.45-0.05 0.4-0.05 1.5±0.1 1.5±0.1 1.5±0.1 1.5±0.1 1.5±0.1 1.5±0.1 1.5±0.1

2-5K1B

Weight: 0.05 g (typ.)

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Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient	R _{th (ch-a)}	250	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

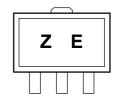
Note 2: Mounted on ceramic substrate (25.4 mm × 25.4 mm × 0.8 mm)

Note 3: $V_{DD} = -50 \text{ V}$, $T_{ch} = 25^{\circ}\text{C}$ (initial), L = 168 mH, $R_G = 25 \Omega$, $I_{AR} = -1 \text{ A}$

Note 4: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.

Marking



(The two digits represent the part number.)



Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I_{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μA
Drain cut-off cur	rent	I _{DSS}	$V_{DS} = -100 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-100	μA
Drain-source brooklage	eakdown	V _{(BR) DSS}	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-100	_	_	٧
Gate threshold v	oltage	V_{th}	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	V
Drain-source ON registeres		R _{DS (ON)}	$V_{GS} = -4 \text{ V}, I_D = -0.5 \text{ A}$	_	1.68	2.5	Ω
Drain-source ON resistance	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$		_	1.34	1.9		
Forward transfer	admittance	Y _{fs}	$V_{DS} = -10 \text{ V}, I_D = -0.5 \text{ A}$	0.3	0.7	_	S
Input capacitano	е	C _{iss}		_	135	_	
Reverse transfer capacitance		C _{rss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	22	_	pF
Output capacitance		C _{oss}		_	48	_	
Switching time	Rise time	t _r	V_{GS} V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT} V_{OUT}	_	20	_	- ns
	Turn-on time	t _{on}		_	32	_	
	Fall time	t _f		_	25	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu \text{s}$	_	130	_	
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ -80 V, V _{GS} = -10 V,	_	6.3	_	
Gate-source charge		Q _{gs}	$I_D = -1 A$		4.1	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	2.2	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	-1	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	-3	Α
Forward voltage (diode)	V _{DSF}	$I_{DR} = -1 \text{ A, } V_{GS} = 0 \text{ V}$	_	_	1.5	V
Reverse recovery time	t _{rr}	I _{DR} = -1 A, V _{GS} = 0 V	1	90		ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 50 A / μs	_	180	_	nC

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